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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

#### Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

#### Details

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Product Status	Obsolete
Core Processor	ARM® Cortex®-M0
Core Size	32-Bit Single-Core
Speed	50MHz
Connectivity	EBI/EMI, I²C, IrDA, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LVD, POR, PWM, WDT
Number of I/O	40
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	A/D 8x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/nuvoton-technology-corporation-america/m054lan

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

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- Up to two sets of UART device
- Programmable baud-rate generator
- Buffered receiver and transmitter, each with 15 bytes FIFO
- Optional flow control function (CTS and RTS)
- Supports IrDA(SIR) function
- Supports RS485 function
- Supports LIN function
- SPI
  - Up to two sets of SPI device.
  - Supports master/slave mode
  - Full duplex synchronous serial data transfer
  - Provide 3 wire function
  - Variable length of transfer data from 1 to 32 bits
  - MSB or LSB first data transfer
  - Rx latching data can be either at rising edge or at falling edge of serial clock
  - Tx sending data can be either at rising edge or at falling edge of serial clock
  - Supports Byte suspend mode in 32-bit transmission
- I<sup>2</sup>C
  - Supports master/slave mode
  - Bidirectional data transfer between masters and slaves
  - Multi-master bus (no central master).
  - Arbitration between simultaneously transmitting masters without corruption of serial data on the bus
  - Serial clock synchronization allows devices with different bit rates to communicate via one serial bus.

- Serial clock synchronization can be used as a handshake mechanism to suspend and resume serial transfer.
- Programmable clocks allow versatile rate control.
- Supports multiple address recognition (four slave address with mask option)
- ADC
  - 12-bit SAR ADC with 760k SPS
  - Up to 8-ch single-ended input or 4-ch differential input
  - Supports single mode/burst mode/single-cycle scan mode/continuous scan mode
  - Supports 2' complement/un-signed format in differential mode conversion result
  - Each channel with an individual result register
  - Supports conversion value monitoring (or comparison) for threshold voltage detection
  - Conversion can be started either by software trigger or external pin trigger
- Analog Comparator
  - Up to 2 comparator analog modules
  - External input or internal band gap voltage selectable at negative node
  - Interrupt when compare result change
  - Power down wake up
- EBI (External Bus Interface) for external memory-mapped device access
  - Accessible space: 64KB in 8-bit mode or 128KB in 16-bit mode
  - Supports 8-bit/16-bit data width
  - Supports byte-write in 16-bit data width
- In-System Programming (ISP) and In-Circuit Programming (ICP)
- One built-in temperature sensor with 1°C resolution
- Brown-Out Detector
  - With 4 levels: 4.3V/3.7V/2.7V/2.2V

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- Supports Brown-Out interrupt and reset option
- 96-bit unique ID
- LVR (Low Voltage Reset)
  - Threshold voltage levels: 2.0V
- Operating Temperature: -40°C~85°C
- Packages:
  - Green package (RoHS)
  - 48-pin LQFP, 33-pin QFN

#### **3 BLOCK DIAGRAM**



Figure 3-1 NuMicro™ M051 Series Block Diagram

#### **4 SELECTION TABLE**

NuMicro M051<sup>™</sup> Series Selection Guide

Part number		DAM [	Data	Data	Data	Data	M Data		1/0	Timer	Con	nectiv	ity	COMP	D/W/M	ADC	ERI	ISP	Package
Fait liulibei	AFROM	N/AIVI	Flash	LDROW	1/0	Timer	UART	SPI	I2C		FVVIVI	ADC	СЫ	ICP	гаскауе				
M052LBN	8KB	4KB	4KB	4KB	40	4x32-bit	2	2	1	2	8	8X12-bit	v	v	LQFP48				
M052ZBN	8KB	4KB	4KB	4KB	24	4x32-bit	2	1	1	2	5	8X12-bit		v	QFN33				
M054LBN	16KB	4KB	4KB	4KB	40	4x32-bit	2	2	1	2	8	8X12-bit	v	v	LQFP48				
M054ZBN	16KB	4KB	4KB	4KB	24	4x32-bit	2	1	1	2	5	8X12-bit		v	QFN33				

Table 4-1 NuMicro™ M051 Series Product Selection Guide





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#### **5 PIN CONFIGURATION**

5.1 QFN 33 pin



Figure 5-1 NuMicro™ M051 Series QFN33 Pin Diagram

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#### 6.2 System Manager

#### 6.2.1 Overview

The following functions are included in system manager section

- System Resets
- System Memory Map
- System management registers for Part Number ID, chip reset and on-chip module reset, multi-functional pin control
- System Timer (SysTick)
- Nested Vectored Interrupt Controller (NVIC)
- System Control registers

#### 6.2.2 System Reset

The system reset includes one of the list below event occurs. For these reset event flags can be read by RSTSRC register.

- The Power-On Reset (POR)
- The low level on the /RESET pin
- Watchdog Time Out Reset (WDT)
- Low Voltage Reset (LVR)
- Brown-Out Detected Reset (BOD)
- CPU Reset
- Software one shot Reset

#### 6.2.3 System Power Architecture

In this device, the power architecture is divided into three segments.

- Analog power from AV<sub>DD</sub> and AV<sub>SS</sub> provides the power for analog module operation.
- Digital power from  $V_{DD}$  and  $V_{SS}$  supplies the power to the internal regulator which provides a fixed 1.8V power for digital operation and I/O pins.

The outputs of internal voltage regulator, which is LDO, require an external capacitor which should be located close to the corresponding pin. The Figure 6-2 shows the power architecture of this device.



Figure 6-2 NuMicro M051<sup>™</sup> Series Power Architecture Diagram

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0x4005_0000 – 0x4005_3FFF	UART0_BA	UART0 Control Registers
0x400D_0000 – 0x400D_3FFF	ACMP_BA	Analog Comparator Control Registers
0x400E_0000 – 0x400E_FFFF	ADC_BA	Analog-Digital-Converter (ADC) Control Registers
0x4011_0000 – 0x4011_3FFF	TMR23_BA	Timer2/Timer3 Control Registers
0x4014_0000 – 0x4014_3FFF	PWMB_BA	PWM4/5/6/7 Control Registers
0x4015_0000 – 0x4015_3FFF	UART1_BA	UART1 Control Registers
System Control Space (0xE000_E	000 ~ 0xE000_EFF	F)
0xE000_E010 – 0xE000_E0FF	SCS_BA	System Timer Control Registers
0xE000_E100 - 0xE000_ECFF	SCS_BA	External Interrupt Controller Control Registers
0xE000_ED00 – 0xE000_ED8F	SCS_BA	System Control Registers

Table 6-1 Address Space Assignments for On-Chip Modules





Figure 6-3 Clock generator block diagram

#### 6.4.1.3 Open-Drain Mode Explanation

Set Px\_PMD(PMDn[1:0]) to 2'b10 the Px[n] pin is in Open-Drain mode and the I/O pin supports digital output function but only with sink current capability, an additional pull-up resister is needed for driving high state. If the bit value in the corresponding bit [n] of Px\_DOUT is "0", the pin drive a "low" output on the pin. If the bit value in the corresponding bit [n] of Px\_DOUT is "1", the pin output drives high that is controlled by the internal pull-up resistor or the external pull high resistor.



#### 6.4.1.4 Quasi-bidirectional Mode Explanation

Set Px\_PMD(PMDn[1:0]) to 2'b11 the Px[n] pin is in Quasi-bidirectional mode and the I/O pin supports digital output and input function at the same time but the source current is only up to hundreds uA. Before the digital input function is performed the corresponding bit in Px\_DOUT must be set to 1. The quasi-bidirectional output is common on the 80C51 and most of its derivatives. If the bit value in the corresponding bit [n] of Px\_DOUT is "0", the pin drive a "low" output on the pin. If the bit value in the corresponding bit [n] of Px\_DOUT is "1", the pin will check the pin value. If pin value is high, no action takes. If pin state is low, then pin will drive strong high with 2 clock cycles on the pin and then disable the strong output drive and then the pin status is control by internal pull-up resistor. Note that the source current capability in quasi-bidirectional mode is only about 200uA to 30uA for V<sub>DD</sub> is form 5.0V to 2.5V



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#### 6.5 I<sup>2</sup>C Serial Interface Controller (Master/Slave)

#### 6.5.1 Overview

 $I^2C$  is a two-wire, bi-directional serial bus that provides a simple and efficient method of data exchange between devices. The  $I^2C$  standard is a true multi-master bus including collision detection and arbitration that prevents data corruption if two or more masters attempt to control the bus simultaneously.

Data is transferred between a Master and a Slave synchronously to SCL on the SDA line on a byte-by-byte basis. Each data byte is 8 bits long. There is one SCL clock pulse for each data bit with the MSB being transmitted first. An acknowledge bit follows each transferred byte. Each bit is sampled during the high period of SCL; therefore, the SDA line may be changed only during the low period of SCL and must be held stable during the high period of SCL. A transition on the SDA line while SCL is high is interpreted as a command (START or STOP). Please refer to the Figure 6-13 for more detail I<sup>2</sup>C BUS Timing.



Figure 6-13 I<sup>2</sup>C Bus Timing

The device's on-chip  $I^2C$  provides the serial interface that meets the  $I^2C$  bus standard mode specification. The  $I^2C$  port handles byte transfers autonomously. To enable this port, the bit ENS1 in I2CON should be set to '1'. The  $I^2C$  H/W interfaces to the  $I^2C$  bus via two pins: SDA (serial data line) and SCL (serial clock line). Pull up resistor is needed on pin SDA and SCL for  $I^2C$  operation as these are open drain pins. When the I/O pins are used as  $I^2C$  port, user must set the pins function to  $I^2C$  in advance.

#### 6.9 Watchdog Timer (WDT)

#### 6.9.1 Overview

The purpose of Watchdog Timer is to perform a system reset when system runs into an unknown state. This prevents system from hanging for an infinite period of time. Besides, this Watchdog Timer supports another function to wakeup chip from power down mode. The watchdog timer includes an 18-bit free running counter with programmable time-out intervals. Table 6-2 show the watchdog timeout interval selection and Figure 6.9-1 shows the timing of watchdog interrupt signal and reset signal.

Setting WTE (WDTCR [7]) enables the watchdog timer and the WDT counter starts counting up. When the counter reaches the selected time-out interval, Watchdog timer interrupt flag WTIF will be set immediately to request a WDT interrupt if the watchdog timer interrupt enable bit WTIE is set, in the meanwhile, a specified delay time (1024 \* T<sub>WDT</sub>) follows the time-out event. User must set WTR (WDTCR [0]) (Watchdog timer reset) high to reset the 18-bit WDT counter to avoid chip from Watchdog timer reset before the delay time expires. WTR bit is cleared automatically by hardware after WDT counter is reset. There are eight time-out intervals with specific delay time which are selected by Watchdog timer interval select bits WTIS (WDTCR [10:8]). If the WDT counter has not been cleared after the specific delay time expires, the watchdog timer will set Watchdog Timer Reset Flag (WTRF) high and reset chip. This reset will last 63 WDT clocks (T<sub>RST</sub>) then chip restarts executing program from reset vector (0x0000 0000). WTRF will not be cleared by Watchdog reset. User may poll WTFR by software to recognize the reset source. WDT also provides wakeup function. When chip is powered down and the Watchdog Timer Wake-up Function Enable bit (WDTR[4]) is set, if the WDT counter reaches the specific time interval defined by WTIS (WDTCR [10:8]), the chip is waken up from power down state. First example, if WTIS is set as 000, the specific time interval for chip to wake up from power down state is 2<sup>4</sup> \*  $T_{WDT}$ . When power down command is set by software, then, chip enters power down state. After  $2^4 * T_{WDT}$  time is elapsed, chip is waken up from power down state. Second example, if WTIS (WDTCR [10:8]) is set as 111, the specific time interval for chip to wake up from power down state is 2<sup>18</sup> \* T<sub>WDT</sub>. If power down command is set by software, then, chip enters power down state. After  $2^{18} * T_{WDT}$  time is elapsed, chip is waken up from power down state. Notice if WTRE (WDTCR [1]) is set to 1, after chip is waken up, software should chip the Watchdog Timer counter by setting WTR(WDTCR [0]) to 1 as soon as possible. Otherwise, if the Watchdog Timer counter is not cleared by setting WTR (WDTCR [0]) to 1 before time starting from waking up to software clearing Watchdog Timer counter is over 1024 \*  $T_{WDT}$ , the chip is reset by Watchdog Timer.

WTIS	Timeout Interval Selection	Interrupt Period	WTR Timeout Interval (WDT_
	I <sub>TIS</sub>	I INT	MIN. I <sub>WTR</sub> ~ MAX. I
000	2 <sup>4</sup> * T <sub>WDT</sub>	1024 * T <sub>WDT</sub>	1.6 ms ~ 104 ms
001	2 <sup>6</sup> * T <sub>WDT</sub>	1024 * T <sub>WDT</sub>	6.4 ms ~ 108.8 m
010	2 <sup>8</sup> * T <sub>WDT</sub>	1024 * T <sub>WDT</sub>	25.6 ms ~ 128 m
011	2 <sup>10</sup> * T <sub>WDT</sub>	1024 * T <sub>WDT</sub>	102.4 ms ~ 204.8 r
100	2 <sup>12</sup> * T <sub>WDT</sub>	1024 * T <sub>WDT</sub>	409.6 ms ~ 512 m
101	2 <sup>14</sup> * T <sub>WDT</sub>	1024 * T <sub>WDT</sub>	1.6384 s ~ 1.7408
	0		Publication Release Date:
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### 8 ELECTRICAL CHARACTERISTICS

#### 8.1 Absolute Maximum Ratings

SYMBOL	PARAMETER	MIN	МАХ	UNIT
DC Power Supply	V <sub>DD</sub> –V <sub>SS</sub>	-0.3	+7.0	V
Input Voltage	VIN	V <sub>SS</sub> -0.3	V <sub>DD</sub> +0.3	V
Oscillator Frequency	1/t <sub>CLCL</sub>	4	24	MHz
Operating Temperature	ТА	-40	+85	°C
Storage Temperature	TST	-55	+150	°C
Maximum Current into $V_{DD}$		-	120	mA
Maximum Current out of $V_{SS}$			120	mA
Maximum Current sunk by a I/O pin			35	mA
Maximum Current sourced by a I/C pin	)		35	mA
Maximum Current sunk by total I/C pins			100	mA
Maximum Current sourced by tota I/O pins			100	mA

Note: Exposure to conditions beyond those listed under absolute maximum ratings may adversely affects the lift and reliability of the device.

		0	_	0.8	V	$V_{DD} = 4.5 V$
XT1[*2]		0	-	0.4	2.	$V_{DD} = 2.5V$
Input High Voltage XT1[*2]		3.5	-	V <sub>DD</sub> +0.2	V	V <sub>DD</sub> = 5.5V
XT1[*2]	VIDS	2.4	-	V <sub>DD</sub> +0.2		$V_{DD} = 3.0V$
Negative going threshold (Schmitt input), /RST	VILS	-0.5	-	$0.2  V_{DD}$	V	are a
Positive going threshold (Schmitt input), /RST	VIHS	$0.7 V_{DD}$	-	V <sub>DD</sub> +0.5	V	Ch the
Internal /RST pin pull up resistor	RRST	40		150	KΩ	So Co
Negative going threshold (Schmitt input), P0/1/2/3/4	VILS	-0.5	-	$0.3  V_{DD}$	V	S S S S S S S S S S S S S S S S S S S
Positive going threshold (Schmitt input), P0/1/2/3/4	VIHS	$0.7  V_{DD}$	-	V <sub>DD</sub> +0.5	V	
Source Current	ISR11	-300	-370	-450	μA	V <sub>DD</sub> = 4.5V, VS = 2.4V
P0/1/2/3/4 (Quasi- bidirectional Mode)	ISR12	-50	-70	-90	μA	V <sub>DD</sub> = 2.7V, VS = 2.2V
bidirectional mode)	ISR13	-40	-60	-80	μA	V <sub>DD</sub> = 2.5V, VS = 2.0V
	ISR21	-20	-24	-28	mA	$V_{DD} = 4.5V, VS = 2.4V$
Source Current P0/1/2/3/4 (Push-pull Mode)	ISR22	-4	-6	-8	mA	V <sub>DD</sub> = 2.7V, VS = 2.2V
(NOGE)	ISR23	-3	-5	-7	mA	$V_{DD} = 2.5V, VS = 2.0V$
014100	ISK11	10	16	20	mA	V <sub>DD</sub> = 4.5V, VS = 0.45V
(Quasi-bidirectional and	ISK12	7	10	13	mA	V <sub>DD</sub> = 2.7V, VS = 0.45V
Push-pull Mode)	ISK13	6	9	12	mA	V <sub>DD</sub> = 2.5V, VS = 0.45V
Brown-Out voltage with BOV_VL [1:0] =00b	VBO2.2	2.0	2.2	2.4	V	V <sub>DD</sub> =5.5V
Brown-Out voltage with BOV_VL [1:0] =01b	VBO2.7	2.5	2.7	2.9	V	V <sub>DD</sub> =5.5V
Brown-Out voltage with BOV_VL [1:0] =10b	VBO3.8	3.5	3.7	3.9	V	V <sub>DD</sub> =5.5V
Brown-Out voltage with BOV_VL [1:0] =11b	VBO4.5	4.1	4.3	4.5	V	V <sub>DD</sub> =5.5V
Hysteresis range of BOD voltage	VBH	30	-	150	mV	V <sub>DD</sub> = 2.5V~5.5V

Notes:

1. /RST pin is a Schmitt trigger input.

2. XTAL1 is a CMOS input.

3. Pins of P0, P1, P2, P3 and P4 can source a transition current when they are being externally driven from 1 to 0. In the condition of  $V_{DD}$ =5.5V, 5he transition current reaches its maximum value when Vin approximates to 2V.

### 8.3 AC Electrical Characteristics

#### 8.3.1 External Crystal



Note: Duty cycle is 50%.

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNITS	CONDITION
Clock High Time	t <sub>CHCX</sub>	20	-	-	nS	CON CO
Clock Low Time	t <sub>CLCX</sub>	20	-	-	nS	0.97
Clock Rise Time	t <sub>CLCH</sub>	-	-	10	nS	1022
Clock Fall Time	t <sub>CHCL</sub>	-	-	10	nS	-0

#### 8.3.2 External Oscillator

PARAMETER	CONDITION	MIN.	TYP.	MAX.	UNIT
Input clock frequency	External crystal	4	12	24	MHz
Temperature	-	-40	-	85	°C
V <sub>DD</sub>	-	2.5	5	5.5	V
Operating current	12 MHz@ V <sub>DD</sub> = 5V	-	1	-	mA

PARAMETER	CONDITION	MIN.	TYP.	MAX.	UNIT
Operation voltage	-	2.5	5	5.5	V
Temperature	-	-40	25	85	°C
Quiescent current	V <sub>DD</sub> =5.5V	-	CtDr	5	uA
Threshold voltage	Temperature=25°	1.7	2.0	2.3	v
	Temperature=-40°	-	2.3	S AN	v
	Temperature=85°	-	1.8	No	v
Hysteresis	-	0	0	0	V

#### 8.4.3 Specification of Low Voltage Reset

#### 8.4.4 Specification of Brown-Out Detector

Parameter	Condition	Min.	Тур.	Max.	Unit
Operation voltage	-	2.5	-	5.5	V
Quiescent current	$AV_{DD} = 5.5V$	-	-	140	μΑ
Temperature	-	-40	25	85	°C
Brown-Out voltage	BOV_VL[1:0]=11	4.1	4.3	4.5	V
	BOV_VL [1:0]=10	3.5	3.7	3.9	V
	BOV_VL [1:0]=01	2.5	2.7	2.9	V
	BOV_VL [1:0]=00	2.0	2.2	2.4	V
Hysteresis	-	30m	-	150m	V

#### 8.4.5 Specification of Power-On Reset (5V)

Parameter	Condition	Min.	Тур.	Max.	Unit
Temperature	-	-40	25	85	°C
Reset voltage	V+	-	2	-	V

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